

Appl. No. 10/807,210
Amtd. Dated July 2, 2005
Reply to Office Action of Apr. 12, 2005

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claim 1 (currently amended): A method for manufacturing an EMI-shielding (electromagnetic interference-shielding) assembly having a substrate, comprising the steps of:

- (a) providing oxygen plasma to clean the substrate;
- (b) ion plating the cleaned substrate with a layer of nickel or phosphorus nickel to form an adhesion layer;
- (c) ion plating the plated substrate with a metal shielding layer; and
- (d) ion plating the plated substrate with a corrosion-resistant layer.

Claim 2 (currently amended): The method of claim 1, wherein the temperature of the substrate should be is maintained below 80 °C during the process any one or more of ion-plating steps (b), (c), and (d).

Claim 3 (currently amended): The method of claim 1, wherein [[the]] any one or more of steps (b), (c), and (d) is performed using a vacuum chamber, and a vacuum pressure of the vacuum chamber is maintained between 1×10^{-6} 1×10^{-6} and 1×10^{-8} 1×10^{-8} Torr during the process of ion-plating.

Claim 4 (original): The method of claim 1, wherein step (a) is performed in a vacuum chamber, and oxygen gas is introduced into the vacuum chamber at a volumetric flow rate of between 200 and 2000 standard cubic centimeters per minute (SCCM).

Appl. No. 10/807,210
Arndt Dated July 2, 2005
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Claim 5 (original): The method of claim 1, wherein in step (b) the adhesion layer is made of nickel or phosphorus nickel.

Claim 6 (original): The method of claim 5, wherein in step (c) the metal shielding layer is made of copper.

Claim 7 (original): The method of claim 6, wherein in step (d) the corrosion-resistant layer is made of stainless steel.

Claim 8 (canceled)

Claim 9 (currently amended): The method of claim [[8]] 1, wherein in step (c) the plated substrate is ion plated with a layer of copper on the ~~nickel or phosphorus~~ nickel adhesion layer.

Claim 10 (currently amended): A method for manufacturing an EMI-shielding (electromagnetic interference-shielding) assembly having a substrate, comprising the steps of:

- (a) cleaning the substrate;
- (b) ion plating the cleaned substrate with an adhesion layer made of a first metal material nickel or phosphorus nickel; and
- (c) ion plating the plated substrate with a shielding layer made of a second metal material.

Claim 11 (currently amended): The method of claim 10, wherein after [[the]] step (c), the substrate is ion plated with a corrosion-resistant layer comprising stainless steel.

Claim 12 (original): The method of claim 10, wherein in step (a), the substrate is cleaned using oxygen plasma.

Claim 13 (currently amended): The method of claim 10, wherein the first metal material is nickel and the second metal material is copper.

Appl. No. 10/807,210
Amtd. Dated July 2, 2005
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Claim 14 (withdrawn): An EMI-shielding assembly, comprising:
a substrate made of plastic material;
an adhesion layer applied to the substrate;
a metal shielding layer adhered to the adhesion layer of the substrate; and
a corrosion-resistant layer adhered to the metal shielding layer.

Claim 15 (withdrawn): The EMI-shielding assembly of claim 14, wherein the adhesion layer is made of nickel.

Claim 16 (withdrawn): The EMI-shielding assembly of claim 14, wherein the adhesion layer is made of phosphorus nickel.

Claim 17 (withdrawn): The EMI-shielding assembly of claim 15, wherein the adhesion has a thickness of 5×10^{-9} to 10×10^{-9} meters.

Claim 18 (withdrawn): The EMI-shielding assembly of claim 14, wherein the metal shielding layer is made of copper.

Claim 19 (withdrawn): The EMI-shielding assembly of claim 18, wherein the metal shielding layer has a thickness of 3×10^{-7} to 6×10^{-7} meters.

Claim 20 (withdrawn): The EMI-shielding assembly of claim 14, wherein the corrosion-resistant layer is made of stainless steel and has a thickness in the range of 2×10^{-8} and 20×10^{-8} meters.

Claim 21 (withdrawn): The EMI-shielding assembly of claim 14, wherein said adhesion layer is made of metal.

Claim 22 (new): The method of claim 1, wherein the adhesion layer has a thickness of 5×10^{-9} to 10×10^{-9} meters.

Claim 23 (new): The method of claim 6, wherein the metal shielding layer has a thickness in the range from 3×10^{-7} to 6×10^{-7} meters.

Claim 24 (new): The method of claim 7, wherein the corrosion-resistant layer

Appl. No. 10/807,210

Arndt. Dated July 2, 2005

Reply to Office Action of Apr. 12, 2005

has a thickness in the range from 2×10^{-8} and 20×10^{-8} meters.